

ABSTRACT OF THE DISCLOSURE

A method for making a multi-layer circuit board 116 having apertures 96, 98 which may be selectively and
5 electrically isolated from electrically grounded member 46 and further having selectively formed air bridges and/or crossover members 104 which are structurally supported by material 112. Each of the apertures 96, 98 selectively receives electrically conductive material 114.